

PDSP16330 MC Pythagoras Processor

DS3240

ISSUE 3.1

November 1998

The PDSP16330 is a high speed digital CMOS IC that converts Cartesian data (Real and Imaginary) into Polar form (Magnitude and Phase), at rates up to 10MHz. Cartesian 16+16 bit 2's complement or Sign-Magnitude data is converted into 16 bit Phase format. The Magnitude output may be scaled in amplitude by powers of 2. The Phase output represents a full 2 x π field to eliminate phase ambiguities.

Polyimide is used as an inter-layer dielectric and as glassivation.

FEATURES

- 10MHz Cartesian to Polar Conversion
- 16-Bit Cartesian Inputs
- 16-Bit Magnitude Output
- 12-Bit Phase Output
- 2's Complement or Sign-Magnitude Input Formats
- Three-state Outputs and Independent
- Data Enables Simplify System Interfacing
 Magnitude Scaling Facility with Overflow Flag
- Less than 400 mW Power Dissipation at 10MHz
- 100 pin CQFP Package

APPLICATIONS

- Digital Signal Processing
- Digital Radio
- Radar Processing
- Sonar Processing
- Robotics

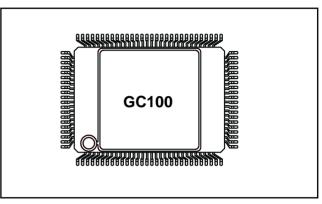


Fig.1 Pin connections - QFP Package

Rev	A	В	С	D	
Date	FEB 1992	MAR 1993	OCT 1995	NOV 1998	

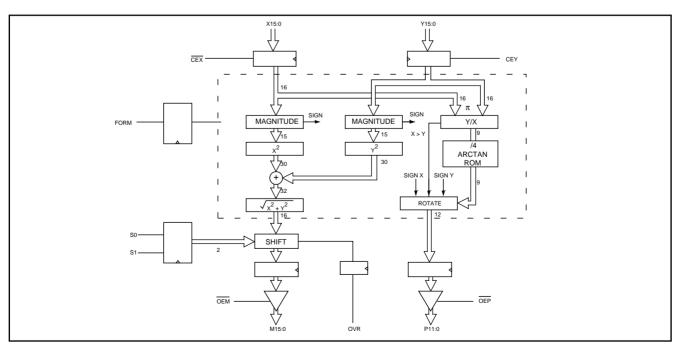
ASSOCIATED PRODUCTS

PDSP16112	16 X 12 Complex Multiplier
PDSP16116	16 X 16 Complex Multiplier
PDSP16318	Complex Accumulator
PDSP16350	I/Q Splitter and NCO
PDSP16510A	Stand Alone FFT Processor

ORDERING INFORMATION

PDSP16330/MC/GC1R

(10MHz - QFP Package, MIL-STD-883 Screening)



FUNCTIONAL DESCRIPTION

The PDSP16330 converts incoming Cartesian Data into the equivalent Polar Values. The device accepts new 16 + 16 bit complex data every cycle, and delivers a 16 bit + 12 bit Polar equivalent after 24 clock cycles. The input data can be in 2s' Complement or Sign Magnitude format selected via the FORM input. The output is in a magnitude format for both the Magnitude output and the Phase. Phase data is zero for data with a zero Y input and positive X, and is 400 hex for zero X data and positive Y, is 800 hex for zero Y data and negative X, and is C00 hex for zero X and negative Y. The LSB weighting (bit 0) is 2 x $\pi/4096$ radians. The 16 bit Magnitude result may be scaled by shifting one, two, or three places in the more significant direction, effectively multiplying the Magnitude result by 2,4 or 8 respectively. Any of these shifts can under certain conditions cause an invalid result to be output from the device. Under these circumstances the OVR output will become active. The PDSP16330 has independent clock enables and three state output controls for all ports.

FORM

This input selects the format of the X and Y input data. A low level on FORM indicates that the Input data is twos' complement format (Note: input data 8000 hex is not valid in 2s' complement mode). This input refers to the format of the current Input data and may be changed on a per cycle basis if desired. The level of FORM is latched at the same time as the data to which it refers.

S1-0

These inputs select the scaling factor to be applied to the Magnitude output. They are latched by the rising edge of CLK and determine the scaling of the output in the cycle after they are loaded into the device. The scale factor applied is determined by the table. Should the scaling factor applied cause an invalid Magnitude result to be output on the M Port, then the OVR Flag will become active for the period that the M Port output is invalid.

S1	S0	Scaling Factor
0	0	x1
0	1	x2
1	0	x4
1	1	x8

The output number range is from 0 to 2 when the scaling factor is set at x1.

PIN DESCRIPTIONS

Symbol	Pin Name and Description
CLK	Clock: Common Clock to device Registers. Register contents change on the rising edge of clock. Both pins must be connected.
CEX	Clock Enable: Clock Enable for X Port. The clock to the X port is enabled by a low level.
CEY	Clock Enable: Clock Enable for Y Port The clock to the Y port is enabled by a low level.
X15-X0	X Data Input Data presented to this input is loaded into the device by the rising edge of CLK. X15 is the MSB
Y15-Y0	Y Data Input Data presented to this input is loaded into the device by the rising edge of CLK. Y15 is the MSB
M15-M0	M Data Output: Magnitude data generated by the device is output on this port. Data changes on the rising edge of CLK, M15 is the MSB. The weighting of M15 is determined by the Scale factor selected.
P11-P0	P Data Output: Phase data generated by the device is output on this port. Data changes on the rising edge of CLK, P11 is the MSB. The weighting of P11 is π radians.
OEM	Output Enable: Output Enable for M Port. The M Port is in a high impedance state when this input is high.
OEP	Output Enable: Output Enable for P Port. The P Port is in a high impedance state when this input is high.
FORM	Format Select This input selects the format of the Cartesian Data input on the X and Y ports. This input is latched by the rising edge of CLK, and is applied at the same time as the data to which it refers. A low level indicates that two's complement data is applied, a high indicates Sign-Magnitude
S1-S0	Scaling Control: Control input for scaling of Magnitude Data. This input is latched by the rising edge of CLK, and determines the scaling to be applied to the Magnitude result. The Scaling is applied to the output data in the cycle following the cycle in which the control was latched.
OVR	Overflow: Overflow flag. This signal becomes active if the scaling currently selected causes an invalid value to be presented to the Magnitude output.
Vcc	+5V supply. All Vcc pins must be connected.
GND	0V supply. All GND pins must be connected.

2's Complement	Sign Magnitude
7FFF	7FFF
	•
0001 0000 FFFF	0001 0000 8000
	•
8001	FFF

INPUT DATA RANGE

Pin No. GC	Function	Pin No. GC	Function	Pin No. GC	Function
	Function M7 M6 M5 M4 M3 M2 M1 M0 S0 S1 GND Vcc FORM Y15 Y14 Y13		Function YO CEY CLK Vcc GND GND GND GND GND GND GND GND GND OEP P0 P1 P2 P3		Function X1 X2 X3 X4 X5 X6 X7 X8 X9 X10 X11 X12 X13 X14 X15 CLK
10 11 12 13 14 15 16 17 18 19 20 21 22	Y12 Y11 Y10 Y9 Y8 Y7 Y6 Y5 Y4 Y3 Y2 Y1	42 43 44 45 46 47 48 49 50 51 52 57 58	P4 P5 P6 P7 P8 P9 P10 P11 GND Vcc CEX X0	75 76 81 82 83 84 85 86 87 88 89 90	OVR Vcc GND OEM M15 M14 M13 M12 M11 M10 M9 M8

PIN FUNCTION

ELECTRICAL CHARACTERISTICS

Test conditions (unless otherwise stated): T_{amb} (Military) =-55°C to + 125°C V_{cc} (Military) = 5.0V \pm 10%, GND = 0V

STATIC CHARACTERISTICS

Characteristic	Symbol	Value			Units	Sub- group	Conditions	
	Cymbol	Min. Typ.		Max.	onito	9.00p	Conditions	
* Output high voltage * Output low voltage	V _{OH} V _{OL}	2.4		0.6	V V	1,2,3 1,2,3	IOH = 3.2mA IOL=-3.2mA	
* Input high voltage (CMOS)	V _{IH}	3.0		1.0	V	1,2,3 1,2,3	Inputs \overline{CEX} , \overline{CEY} and CLK only	
* Input low voltage (CMOS) * Input high voltage (TTL)	V V _{IL}	2.2		1.0	V V	1,2,3	Inputs CEX, CEY and CLK only All other inputs	
* Input low voltage (TTL)* Input leakage current (Note 1)	V _{IL} I _{IL}	-10		0.8 + 120	V μA	1,2,3 1,2,3	All other inputs GND $\leq V_{IN} \leq V_{CC}$	
† Input capacitance* Output leakage current	C _{IN}	-50	10	+ 50	pF μA	1,2,3	GND ≤V _{IN} ≤ V _{cc}	
† Output SC current	I _{OS}	-50		230	mΑ	.,_,0	$V_{cc} = Max$	

NOTES

1. All inputs except clock inputs have high value pull-down resistors

2. All parameters marked * are tested during production. Parameters marked † are guaranteed by design and characterisation.

SWITCHING CHARACTERISTICS

Value			Sub-	
PDSP	PDSP16330		group	Conditions
Min.	Max.	1		
15 2 30 0 15 7 5 100 25 25 24	40 24 30 30 30 30 110 70	ns ns ns ns ns ns ns ns cycles ns ns ns mA mA	9,10,11	2 x LSTTL + 20pF 2 x LSTTL + 20pF 2 x LSTTL + 20pF 2 x LSTTL + 20pF 2 x LSTTL + 20pF V _{cc} = Max Outputs unloaded Clock freq. = Max V_{cc} = Max Outputs unloaded
	PDSP Min. 15 2 30 0 15 7 5 100 25 25	PDSP16330 Min. Max. 15 2 30 0 15 7 5 40 100 25 25 24 24 30 30 30 30 110	PDSP16330 Units Min. Max. Ins 15 ns ns 30 ns ns 0 ns ns 15 ns ns 7 ns ns 5 40 ns 100 ns ns 25 ns ns 30 ns ns 110 mA Na	PDSP16330 Units group Min. Max. ns 15 ns ns 30 ns ns 0 ns ns 15 ns ns 7 ns s 5 40 ns 100 ns 9,10,11 25 ns 30 24 24 cycles 30 ns 30 30 ns 30 30 ns 30 110 mA Horder

NOTES

- 1. LSTTL is equivalent to $I_{OH} = 20\mu A$, $I_{OL} = -0.4mA$ 2. Current is defined as negative into the device 3. CMOS input levels are defined as: $V_{IH} = V_{DD} 0.5V$, $V_{IL} = +0.5V$ 4. All parameters marked * are tested during production. Parameters marked † are guaranteed by design and characterisation.
- 5. All timings are dependent on silicon speed. This speed is tested by measuring clock period. This guarantees all other timings by characterisation and design.

ABSOLUTE MAXIMUM RATINGS

Supply voltage, V _{cc}	-0.5V to + 7.0V
Input voltage, V _{IN}	-0.5V to VCC + 0.5V
Output voltage, V _{our}	-0.5V to VCC + 0.5V
Clamp diode current per pin, I_{κ} (see No	ote 2) ±18mA
Static discharge voltage (HMB), V _{STAT}	500V
Storage temperature. T _{sta}	-65°C to + 150°C
Ambient temperature with	
power applied T _{amb} :	
Military	-55 °C to + 125 °C
Package power dissipation $P_{_{TOT}}$	1200mW
Junction temperature	150 °C

THERMAL CHARACTERISTICS

Package Type	<i>θ</i> υc° C/W
GC	12

NOTES

- 1. Exceeding these ratings may cause permanent damage.
- Functional operation under these conditions is not implied.
- 2. Maximum dissipation or 1 second should not be exceeded;
- only one output to be tested at any one time.
- 3. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability

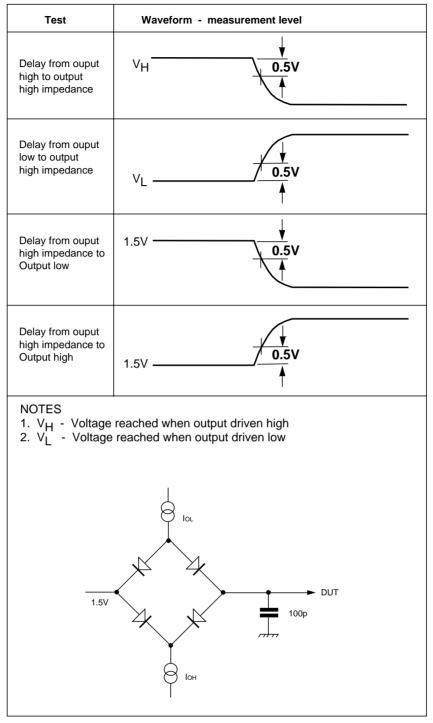


Fig.2 Three state delay measurement load

Part No:

PDSP16330/A Pythagoras Processor

Package Type: AC84/GC100

Pin No.4 GC	Con.	Pin No. GC	Con.	Pin No. GC	Con.	Pin No. GC	Con.
76	V1	49	N/C	41	N/C	6	V1
74	V1	84	N/C	37	0v	7	0v
73	0v	82	0v	42	N/C	10	V1
71	0v	70	0v	93	N/C	13	V1
68	0v	66	0v	94	N/C	15	V1
67	0v	65	0v	92	N/C	19	V1
64	0v	50	N/C	40	N/C	22	V1
61	0v	48	N/C	38	0v	25	V1
59	0v	86	N/C	39	N/C	31	0v
58	0v	85	N/C	96	N/C	33	0v
51	0v	47	N/C	97	N/C	1	0v
83	N/C	46	N/C	35	0v	8 9	V1
81	0v	89	N/C	36	0v	9	V1
75	N/C	88	N/C	98	N/C	11	V1
72	0v	87	N/C	100	V1	14	V1
69	0v	45	N/C	12	V1	20	V1
62	0v	44	N/C	16	V1	18	V1
63	0v	43	N/C	17	V1	21	V1
60	0v	95	N/C	32	0v	23	V1
57	0v	90	N/C	34	0v	24	0v
52	V1	91	N/C	99	V1	26	V1

VDD max = +5.0V = V1

N/C = not connected

(All GC100 pins not specified are N/C)

Fig.3 Life Test/Burn-in connections NOTE: PDA is 5% and based on groups 1 and 7



For more information about all Zarlink products visit our Web Site at

www.zarlink.com

Information relating to products and services furnished herein by Zarlink Semiconductor Inc. or its subsidiaries (collectively "Zarlink") is believed to be reliable. However, Zarlink assumes no liability for errors that may appear in this publication, or for liability otherwise arising from the application or use of any such information, product or service or for any infringement of patents or other intellectual property rights owned by third parties which may result from such application or use. Neither the supply of such information or purchase of product or service conveys any license, either express or implied, under patents or other intellectual property rights owned by Zarlink or licensed from third parties by Zarlink, whatsoever. Purchasers of products are also hereby notified that the use of product in certain ways or in combination with Zarlink, or non-Zarlink furnished goods or services may infringe patents or other intellectual property rights owned by Zarlink.

This publication is issued to provide information only and (unless agreed by Zarlink in writing) may not be used, applied or reproduced for any purpose nor form part of any order or contract nor to be regarded as a representation relating to the products or services concerned. The products, their specifications, services and other information appearing in this publication are subject to change by Zarlink without notice. No warranty or guarantee express or implied is made regarding the capability, performance or suitability of any product or service. Information concerning possible methods of use is provided as a guide only and does not constitute any guarantee that such methods of use will be satisfactory in a specific piece of equipment. It is the user's responsibility to fully determine the performance and suitability of any equipment using such information and to ensure that any publication or data used is up to date and has not been superseded. Manufacturing does not necessarily include testing of all functions or parameters. These products are not suitable for use in any medical products whose failure to perform may result in significant injury or death to the user. All products and materials are sold and services provided subject to Zarlink's conditions of sale which are available on request.

Purchase of Zarlink's I²C components conveys a licence under the Philips I²C Patent rights to use these components in and I²C System, provided that the system conforms to the I²C Standard Specification as defined by Philips.

Zarlink, ZL and the Zarlink Semiconductor logo are trademarks of Zarlink Semiconductor Inc.

Copyright Zarlink Semiconductor Inc. All Rights Reserved.

TECHNICAL DOCUMENTATION - NOT FOR RESALE